

1        1.    A method comprising:  
2                positioning a wafer between a pair of rotating  
3 brushes; and  
4                providing a cleaning solution through at least  
5 one of said brushes.

1        2.    The method of claim 1 including providing a  
2 cleaning solution through the center of each of said  
3 brushes.

1        3.    The method of claim 1 wherein providing a  
2 cleaning solution includes providing a solution of  
3 deionized water and a cleaning chemical.

1        4.    The method of claim 1 including spraying a  
2 solution at the interface between said rotating brushes and  
3 said wafer.

1        5.    The method of claim 4 including using a spray bar  
2 to spray the solution.

1        6.    The method of claim 5 including spraying the  
2 deionized water at the interface between the brushes and  
3 wafers.

1        7.    The method of claim 1 including providing the  
2    cleaning solution to both of said brushes.

1        8.    The method of claim 1 including cleaning wafers  
2    after chemical mechanical polishing.

1        9.    An apparatus comprising:  
2                a pair of rotatable brushes to receive a wafer  
3    between said brushes; and  
4                a cleaning solution dispenser to dispense  
5    cleaning solution from the interior of said brushes and to  
6    flow outwardly through the brushes to the brush wafer  
7    interface.

1        10.   The apparatus of claim 9 including spray bars to  
2    spray liquid at the brush wafer interface.

1        11.   The apparatus of claim 10 wherein said spray bars  
2    are coupled to a source of deionized water.

1        12.   The apparatus of claim 9 including a reservoir to  
2    supply a source of cleaning solution.

1        13.   The apparatus of claim 12 including a mixer to  
2    mix deionized water and a cleaning chemical to form the  
3    cleaning solution.

1        14. The apparatus of claim 9 including a pipe that  
2 provides a cleaning solution to the center of each of said  
3 brushes and ejects said cleaning solution radially  
4 outwardly through said brushes.

1        15. An apparatus for cleaning semiconductor wafers  
2 after chemical mechanical polishing comprising:  
3            a pair of counter-rotating brushes to receive a  
4 wafer to be cleaned between said brushes;  
5            a pair of spray bars to spray deionized water at  
6 the brush wafer interface; and  
7            a cleaning solution dispenser to dispense  
8 cleaning solution from the center of each of said brushes  
9 to flow outwardly through the brushes to the brush wafer  
10 interface.

1        16. The apparatus of claim 15 including a mixer to  
2 mix deionized water and a cleaning chemical to form a  
3 cleaning solution.

1        17. The apparatus of claim 15 including a pipe that  
2 extends through each of said brushes to dispense the  
3 cleaning solution from the center of said brushes.